Docket No.: JCLA27920

Form 1595 (Rev. 09/04) RECORDATION FORM (	COVER SHEET U. S. Department of Commerce Patent and Trademark Office	
PATENTS ONLY		
To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below		
Name of conveying party(ies) with the execution date:	2. Name/address of receiving Party(ies)	
MEI-LING CHAO, July 22, 2008 CHIA-YUN CHEN, July 22, 2008 TAI-HSIANG LAI, July 22, 2008 TIEN-HAO TANG, July 22, 2008	UNITED MICROELECTRONICS CORP.  NO. 3, LI-HSIN RD. II, SCIENCE-BASED INDUSTRIAL PARK, HSINCHU, TAIWAN, R.O.C.	
3. Nature of conveyance:   x Assignment Security Agreement  Merger Change of Name  Reassignment Other  4. Application number(s) or patent number(s)	Add'1 names of receiving parties Attached? Yes X No	
A. Patent Application No. (s)	B. Patent No.(s)	
12/178,058		
Additional number attached?  5. Name and address of party to whom correspondence concerning document should be mailed:  J. C. Patents 4 Venture, Suite 250 Irvine, CA 92618 (949) 660-0761  Atty Docket No.: JCLA27920  9. Statement and Signature:	Yes   x   No	
To the best of my knowledge and be Correct and any attached copy is a t	lief, the forging information is true and rue copy of the original document.	
Jiawei Huang Name of person Signing Registration No. 43,330	7-23-2008 Total number of pages including cover sheet, attachments, and documents: 3	

**PATENT** 

REEL: 021288 FRAME: 0582

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## ASSIGNMENT

## WHEREAS,

1. Mei-Ling Chao

2. Chia-Yun Chen

3. Tai-Hsiang Lai

4. Tien-Hao Tang

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: DEVICE FOR ESD PROTECTION CIRCUIT

[ ] Filed:

Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, United Microelectronics Corp.

of No. 3, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

Fourth Joint Inventor (if any): Tien-Hao Lang

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## **ASSIGNMENT CONTINUED**

IN TESTIMONY WHEREOF, As signor has/have signed his/her/their name(s) on the date(s) indicated.

signature: Mel-Ling Chao	Date: _July 22, 2008
Sole or First Joint Inventor: Mei-Ling Chao	
Signature: Chia Ym Chen	Date: July 22, 2008
Second Joint Inventor (if any): Chia-Yun Chen	
Signature: Jai - Asiang Lui	Date: July 22, 2008
Third Joint Inventor (if any): Tai-Hslang Lal	
Signature: Zin-How Tary	Date: July 22, 2008